

Electronic Patent Application Fee Transmittal

Application Number:	10789914
Filing Date:	27-Feb-2004
Title of Invention:	RESIN COMPOSITION, PREPREG, LAMINATE, AND SEMICONDUCTOR PACKAGE
First Named Inventor/Applicant Name:	Takeshi Hosomi
Filer:	Robert M. Siminski/janice ogg
Attorney Docket Number:	2497-000002/CP

Filed as Large Entity

Utility Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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Basic Filing:

Pages:

Claims:

Miscellaneous-Filing:

Petition:

Patent-Appeals-and-Interference:

Post-Allowance-and-Post-Issuance:

Utility Appl issue fee	1501	1	1400	1400
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Miscellaneous:				
Total in USD (\$)				1700